



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: William T. Chen )  
Application No.: 10/029,435 )  
Filed: 12/18/2001 )  
For: "Method of forming )  
selective electroless plating )  
on polymer surfaces" )  
Group Art No.: 1762  
Examiner: Padgett, Marianne L  
Re: Response  
Our Ref: B-4361 619261-9  
Date: May 5, 2004

FEES FOR EXCESS CLAIMS

Commissioner for Patents  
POB 1450  
Alexandria, VA 22313-1450

Sir:

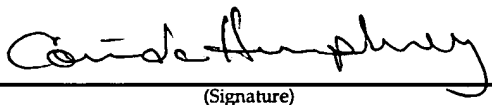
1. This is a paper showing the calculation of excess claim fees.
2. Applicant is a small entity.
3. An amendment is filed concurrently with this petition.
4. Attached is a check for the sum of \$9.00. Charge to Deposit Account No. 12-0415 any additional fee required or credit for any excess fee paid.
5. The fees are calculated as follows:

CLAIMS	CURRENT NUMBER	HIGHEST NUMBER PREVIOUSLY PAID FOR	NUMBER EXTRA	RATE	AMOUNT
Total	21	20	= 1	X \$18.00/2	\$9.00
Independent	2	3	= 0	X \$86.00/2	\$00.00
				<b>TOTAL</b>	<b>\$9.00</b>

I hereby certify that this correspondence is being deposited with the United States Post Office with sufficient postage as first class mail in an envelope addressed to Commissioner for Patents, POB 1450, Alexandria, VA 22313-1450 on

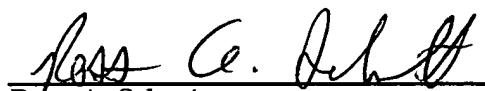
May 5, 2004  
(Date of Deposit)

Corinda Humphrey

  
(Signature)

May 5, 2004  
(Date)

Respectfully submitted,

  
Ross A. Schmitt  
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